



MODEL:

TANK-XM811 Series

**Embedded System with 10th/11th Generation Intel® Core™ Processor,
Two DDR4 Slot, Digital I/O, HDMI, DP, Two Gigabit Ethernet, RS-232/422/485,
RoHS Compliant**

User Manual

Revisions

Date	Version	Changes
July 18, 2022	1.00	Initial release

Copyright

COPYRIGHT NOTICE

The information in this document is subject to change without prior notice in order to improve reliability, design and function and does not represent a commitment on the part of the manufacturer.

In no event will the manufacturer be liable for direct, indirect, special, incidental, or consequential damages arising out of the use or inability to use the product or documentation, even if advised of the possibility of such damages.

This document contains proprietary information protected by copyright. All rights are reserved. No part of this manual may be reproduced by any mechanical, electronic, or other means in any form without prior written permission of the manufacturer.

TRADEMARKS

All registered trademarks and product names mentioned herein are used for identification purposes only and may be trademarks and/or registered trademarks of their respective owners.

Manual Conventions



WARNING

Warnings appear where overlooked details may cause damage to the equipment or result in personal injury. Warnings should be taken seriously.



CAUTION

Cautionary messages should be heeded to help reduce the chance of losing data or damaging the product.



NOTE

These messages inform the reader of essential but non-critical information. These messages should be read carefully as any directions or instructions contained therein can help avoid making mistakes.



HOT SURFACE

This symbol indicates a hot surface that should not be touched without taking care.

Table of Contents

1 INTRODUCTION.....	1
1.1 OVERVIEW.....	2
1.2 MODEL VARIATIONS	3
1.3 FEATURES.....	3
1.4 TECHNICAL SPECIFICATIONS	4
1.5 FRONT PANEL.....	6
1.6 REAR PANEL.....	7
1.7 PHYSICAL DIMENSIONS	8
2 UNPACKING	9
2.1 ANTI-STATIC PRECAUTIONS	10
2.2 UNPACKING PRECAUTIONS.....	10
2.3 UNPACKING CHECKLIST	11
3 INSTALLATION	16
3.1 INSTALLATION PRECAUTIONS	17
3.2 BACK COVER REMOVAL.....	17
3.3 CPU INSTALLATION	18
3.4 MEMORY INSTALLATION.....	20
3.5 STORAGE INSTALLATION	21
3.5.1 M.2 SSD Installation.....	21
3.5.2 2.5-inch SSD Installtion.....	22
3.6 WI-FI MODULE INSTALLATION (OPTIONAL).....	23
3.7 BACK COVER INSTALLATION.....	24
3.8 MOUNTING THE SYSTEM WITH MOUNTING BRACKETS	24
3.9 EXTERNAL PERIPHERAL INTERFACE CONNECTORS.....	25
3.9.1 AT/ATX Power Mode Selection.....	26
3.9.2 System Fan Connector	26
3.9.3 Digital Input / Output Connector.....	27
3.9.4 HDMI/DP Connector.....	28

3.9.5 LAN Connectors.....	28
3.9.6 Power Input, 4-pin Terminal Block.....	30
3.9.7 Power Input, 4-pin DIN Connector	30
3.9.8 DB-9 RS-232/422/485 Serial Port Connectors.....	31
3.9.9 Remote Power Connector	31
3.10 POWERING ON/OFF THE SYSTEM	32
3.11 POWER	33
3.12 AVAILABLE DRIVERS	35
3.12.1 Driver Download	35
3.13 MAINTENANCE.....	37
3.13.1 Flash Descriptor Security Override Jumper.....	37
4 SYSTEM MOTHERBOARD	39
4.1 OVERVIEW.....	40
4.1.1 Layout	40
4.2 INTERNAL PERIPHERAL CONNECTORS	42
4.2.1 Clear CMOS Switch (J_CMOS1).....	43
4.2.2 BIOS Programming Connector (JSPII)	43
4.2.3 EC Programming Connector (EC_SPII).....	43
4.2.4 EC Debug Card Connector (DEBUG_SPII).....	44
4.2.5 System Fan Connector (SYS_FAN1)	44
4.2.6 Battery Connector (BAT1)	44
4.3 EXTERNAL INTERFACE PANEL CONNECTORS	44
4.3.1 LAN Connectors.....	45
4.3.2 Power Input Connector, DC Jack (PWR1)	46
4.3.3 Power Input Connector, Terminal Block (PWR2).....	46
A REGULATORY COMPLIANCE	47
B SAFETY PRECAUTIONS	52
B.1 SAFETY PRECAUTIONS.....	53
B.1.1 General Safety Precautions	53
B.1.2 Anti-static Precautions	54
B.1.3 Product Disposal	55
B.2 MAINTENANCE AND CLEANING PRECAUTIONS	55
B.2.1 Maintenance and Cleaning.....	56

TANK-XM811

<i>B.2.2 Cleaning Tools</i>	56
C ERROR BEEP CODE	57
C.1 PEI BEEP CODES	58
C.2 DXE BEEP CODES	58
D HAZARDOUS MATERIALS DISCLOSURE	59
D.1 RoHS II DIRECTIVE (2015/863/EU)	60
D.2 CHINA RoHS.....	61

List of Figures

Figure 1-1: TANK-XM811 Series.....	2
Figure 1-2: Front Panel	6
Figure 1-3: Rear Panel.....	7
Figure 1-4: Physical Dimensions	8
Figure 3-1: Remove the Cover.....	18
Figure 3-2: Motherboard Removal	18
Figure 3-3: CPU Installation.....	19
Figure 3-4: CPU Thermal Pad Installation	19
Figure 3-5: Motherboard Installation	20
Figure 3-6: Memory Installation	21
Figure 3-7: M.2 Installation.....	22
Figure 3-8: HDD Installation	22
Figure 3-9: Wi-Fi Module and Wi-Fi Antenna Installation	24
Figure 3-10: Back Cover Installation	24
Figure 3-11: Mounting Bracket Retention Screws	25
Figure 3-12: AT/ATX Power Mode Switch	26
Figure 3-13: SYS_FAN Connector.....	27
Figure 3-14: DIO Connector.....	28
Figure 3-15: HDMI/DP Connection	28
Figure 3-16: LAN Connection	29
Figure 3-17: RJ-45 Ethernet Connector.....	29
Figure 3-18: 4-pin Terminal Block.....	30
Figure 3-19: Power Input Connector.....	30
Figure 3-20: DB-9 RS-232/422/485 Serial Port Connector	31
Figure 3-21: Remote Power Connector	32
Figure 3-22: Power Button.....	33
Figure 3-23: Power Connectors	34
Figure 3-24: IEI Resource Download Center.....	35
Figure 3-25 Flash Descriptor Security Override Jumper Location.....	37
Figure 4-1: System Motherboard (Front).....	40

TANK-XM811

Figure 4-2: System Motherboard (Rear)	41
Figure 4-3: Ethernet Connector	45

List of Tables

Table 1-1: TANK-XM811 Series Model Variations	3
Table 1-2: Technical Specifications.....	5
Table 3-1: Digital I/O Connector Pinouts.....	27
Table 3-2: RJ-45 Ethernet Connector LEDs	29
Table 3-3: RS-232 (COM1~COM4) & RS-232/422/485 (COM5~COM6) Connector Pinouts	31
Table 3-4: Power LED Indicators Description.....	34
Table 3-5: Flash Descriptor Security Override Jumper Settings	37
Table 4-1: Peripheral Interface Connectors	42
Table 4-2: Clear CMOS Switch (J_CMOS1).....	43
Table 4-3: BIOS Programming Connector Pinouts (JSPI1).....	43
Table 4-4: EC Programming Connector (EC_SPI1).....	43
Table 4-5: EC Debug Card Connector (DEBUG_SPI1).....	44
Table 4-6: System Fan Connector (SYS_FAN1)	44
Table 4-7: Battery Connector (BAT1).....	44
Table 4-8: Rear Panel Connectors	45
Table 4-9: Ethernet Connector Pinouts	45
Table 4-10: Connector LEDs.....	46
Table 4-11: Power Input Connector (PWR1)	46
Table 4-12: Power Input Connector (PWR2)	46

Chapter

1

Introduction

1.1 Overview

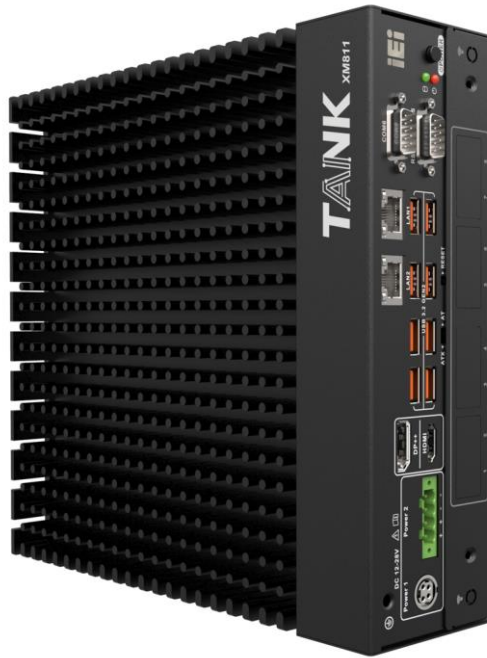


Figure 1-1: TANK-XM811 Series

The TANK-XM811 Series is an embedded system for wide range temperature environments. It is powered by 12th generation Intel® Core™ processor with Intel® Q470 chipset, and has two 260-pin DDR4 SDRAM SO-DIMM slots supporting up to 64GB memory (8GB preinstalled). The TANK-XM811 Series includes one digital I/O port, one HDMI, one DP, two GbE LAN, eight USB 3.2 Gen 2, two RS-232/422/485 and four RS-232 connectors.

TANK-XM811

1.2 Model Variations

The model variations of the TANK-XM811 Series are listed below.

Model No.	CPU
TANK-XM811-i5AC-R10	Intel® Core™ i5-12500TE 1.9GHz (up to 4.3GHz, 6-core, TDP 35W)
TANK-XM811-i7AC-R10	Intel® Core™ i7-12700TE 1.4GHz (up to 4.6GHz, 12-core, TDP 35W)
TANK-XM811-i9D-R10	Intel® Core™ i9-12900TE 1.1GHz (up to 4.8GHz, 16-core, TDP35W)

Table 1-1: TANK-XM811 Series Model Variations

1.3 Features

The TANK-XM811 Series features are listed below:

- 12th Gen. Intel® Core™ processor platform with Intel® R680E chipset and DDR4 memory
- Dual independent displays with high resolution support
- Rich high-speed I/O interfaces
- One 2.5" HDD/SSD SATA 6Gb/s bay
- Great flexibility for hardware expansion

1.4 Technical Specifications

The TANK-XM811 Series technical specifications are listed in Table 1-2

Specifications	
Chassis	
Color	Black C
Dimensions (WxDxH) (mm)	230.6 x 256.04 x 76.2
System Fan	Fanless
Chassis Construction	Extruded aluminum alloy
Motherboard	
CPU	12th Gen. Intel® Core™ CPU: Intel® Core™ i9-12900TE 1.1GHz (up to 4.8GHz, 16-core, TDP 35W) Intel® Core™ i7-12700TE 1.4GHz (up to 4.6GHz, 12-core, TDP 35W) Intel® Core™ i5-12500TE 1.9GHz (up to 4.3GHz, 6-core, TDP 35W)
Chipset	Intel® R680E
System Memory	2 x SO-DIMM DDR4 3200MHz (up to 64GB)
Storage	
Hard Drive	1 x 2.5" HDD/SSD SATA 6Gb/s bay
I/O Interfaces	
USB 3.2 Gen 2 (10Gb/s)	8
RS-232/422/485	2 x RS-232/422/485 2 x RS232
Ethernet	Two RJ-45 2 x Intel 2.5GbE by Intel® I225 controller
TPM 2.0	Intel PTT
Digital I/O	12-bit (6-in/6-out)
Display	HDMI/DP++
Expansions	

TANK-XM811

Specifications	
M.2	1 x 2280 M key (PCIe x4) 1 x 2230 A-key (USB+PCIe x1, supports vPRO)
Backplane	Optional
Power	
Power Input	DC jack: 12 V~28 V DC Terminal block: 12 V~28 V DC
Power Consumption	12V @ 8.8A (Intel® Core™ i9-12900TE with 16GB memory)
Remote Power	1 x 2-pin
Reliability	
Mounting	Wall mount
Operating Temperature	-20°C ~ 60°C with air flow (CPU TDP 35W & SSD) -20°C ~ 50°C with air flow (CPU TDP 65W & SSD), 10% ~ 95% non-condensing
Storage Temperature	-40°C ~ 85°C, 10% ~ 95%, non-condensing
Operating Shock	Half-sine wave shock 5G, 11ms, 100 shocks per axis (SSD)
Operating Vibration	MIL-STD-810G 514.6C-1 (with SSD)
Weight (Net/Gross)	3.33 kg / 3.7 kg
Safety/EMC	CE/FCC
Watchdog Timer	Programmable 1~255 sec/min
OS	
Supported OS	Microsoft Windows 10 IoT Enterprise / Windows 11 Linux

Table 1-2: Technical Specifications

1.5 Front Panel

The front panel of the TANK-XM811 Series has the following features (**Figure 1-2**):

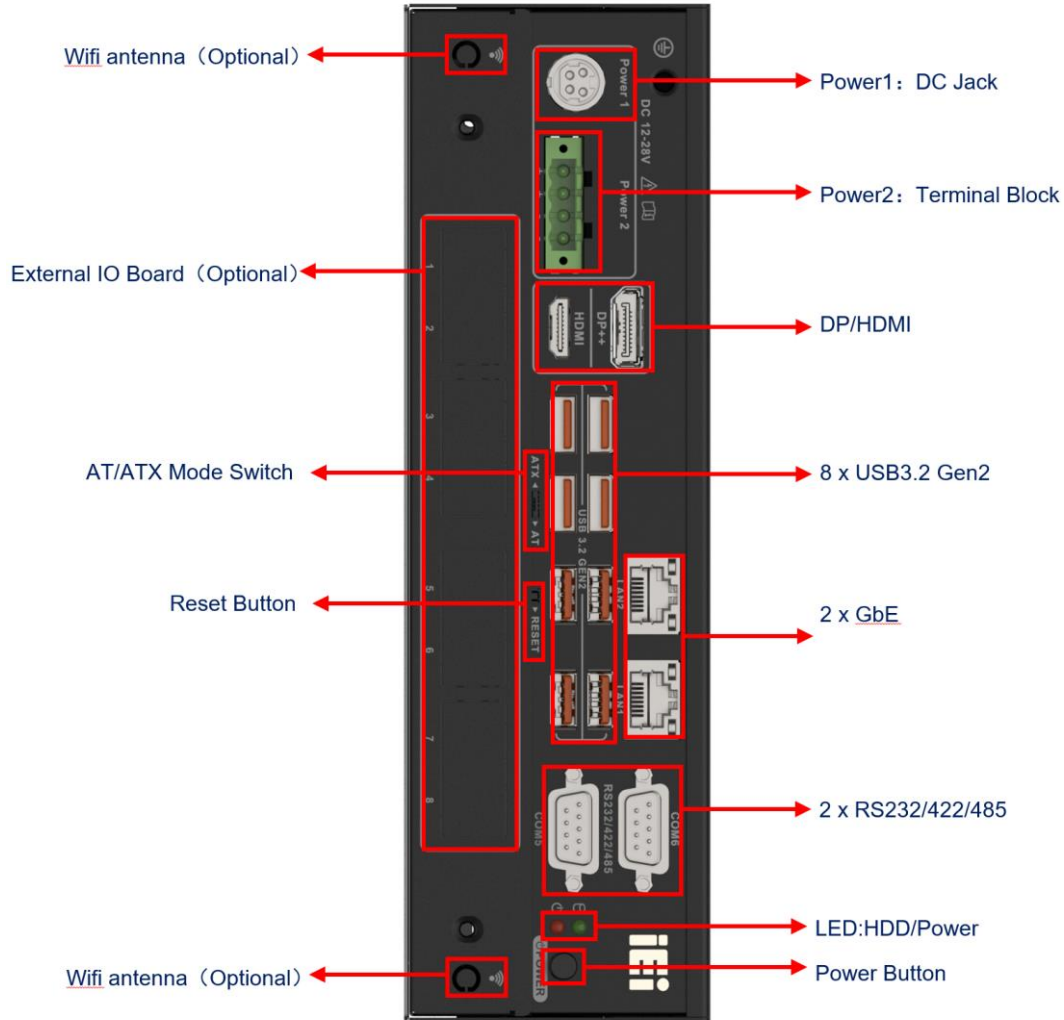


Figure 1-2: Front Panel

TANK-XM811

1.6 Rear Panel

The rear panel of the TANK-XM811 Series is shown below.

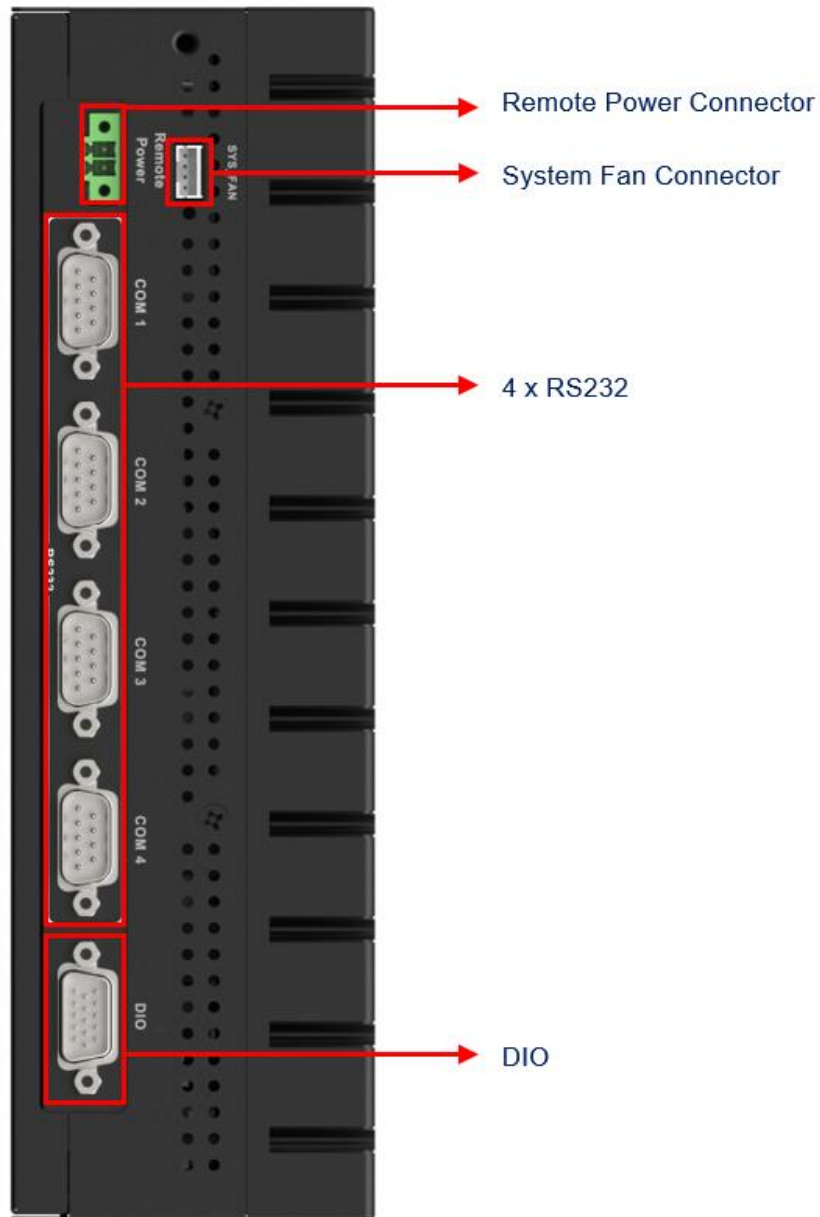


Figure 1-3: Rear Panel

1.7 Physical Dimensions

The physical dimensions of the TANK-XM811 are shown in **Figure 1-4**.

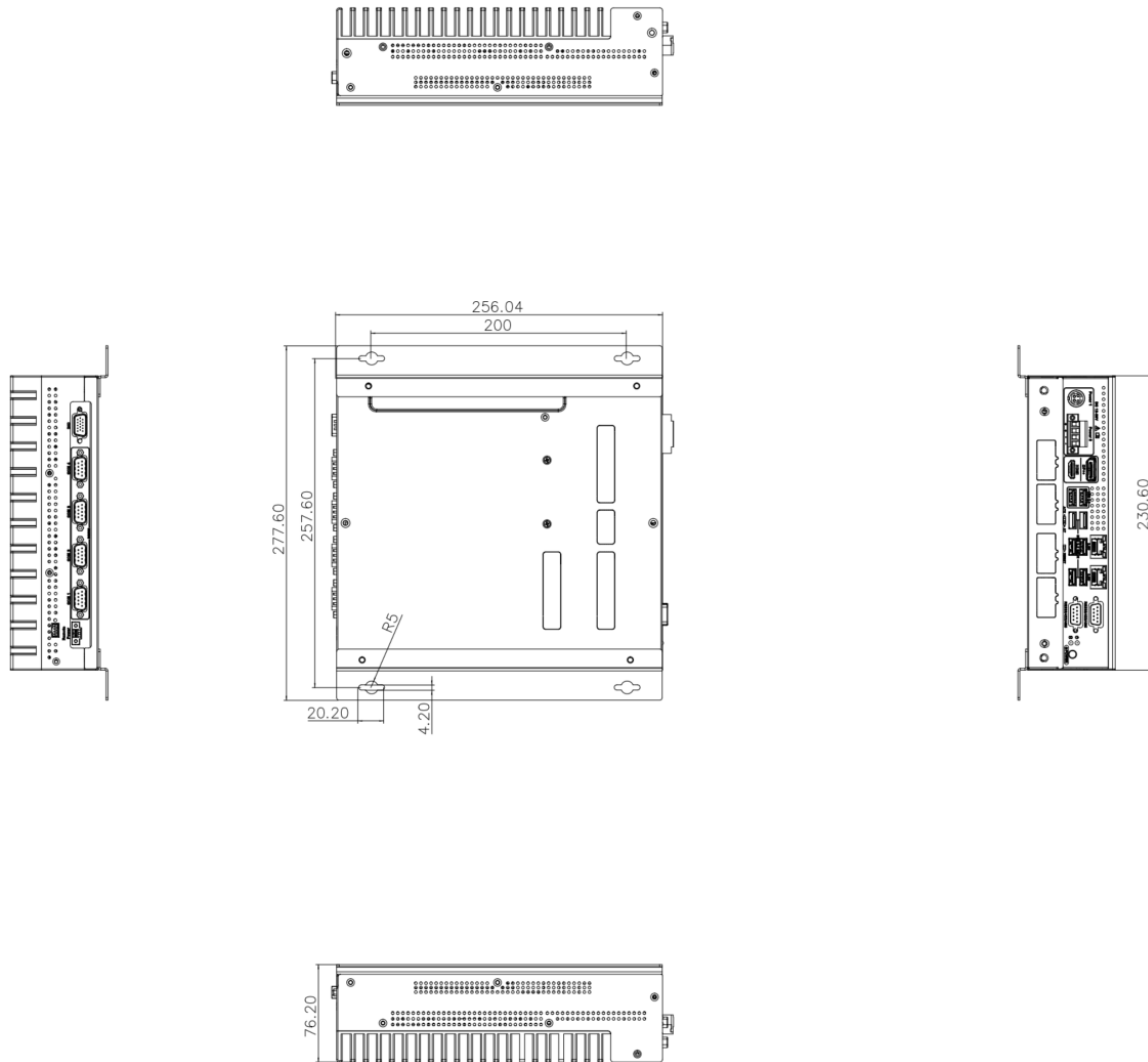


Figure 1-4: Physical Dimensions

Chapter

2

Unpacking

2.1 Anti-static Precautions



WARNING:

Failure to take ESD precautions during installation may result in permanent damage to the TANK-XM811 Series and severe injury to the user.

Electrostatic discharge (ESD) can cause serious damage to electronic components, including the TANK-XM811 Series. Dry climates are especially susceptible to ESD. It is therefore critical that whenever the TANK-XM811 Series or any other electrical component is handled, the following anti-static precautions are strictly adhered to.

- **Wear an anti-static wristband:** Wearing a simple anti-static wristband can help to prevent ESD from damaging the board.
- **Self-grounding:** Before handling the board touch any grounded conducting material. During the time the board is handled, frequently touch any conducting materials that are connected to the ground.
- **Use an anti-static pad:** When configuring the TANK-XM811 Series, place it on an anti-static pad. This reduces the possibility of ESD damaging the TANK-XM811 Series.

2.2 Unpacking Precautions

When the TANK-XM811 Series is unpacked, please do the following:

- Follow the anti-static precautions outlined in **Section 2.1**.
- Make sure the packing box is facing upwards so the TANK-XM811 Series does not fall out of the box.
- Make sure all the components shown in **Section 2.2** are present.

TANK-XM811

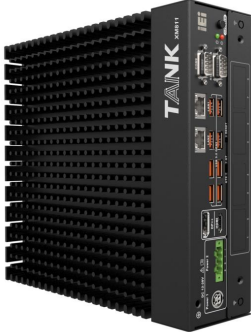

2.3 Unpacking Checklist






NOTE:


If some of the components listed in the checklist below are missing, please do not proceed with the installation. Contact the IEI reseller or vendor you purchased the TANK-XM811 Series from or contact an IEI sales representative directly. To contact an IEI sales representative, please send an email to sales@ieiworld.com.

The TANK-XM811 Series is shipped with the following components:







Quantity	Item and Part Number	Image
Standard		
1	TANK-XM811 series	
2	Mounting brackets	

Quantity	Item and Part Number	Image
Standard		
1	2-pin terminal block	
1	4-pin terminal block	
1	Chassis screws	

The following table lists the optional items that can be purchased separately.






Optional	
Wi-Fi module (P/N: EMB-WIFI-KIT02I3-R10)	

TANK-XM811

Optional	
<p>Power adapter (P/N: 63040-010180-200-RS)</p>	
<p>Power cord (P/N: 32000-000002-RS)</p>	
<p>8-Port POE LAN card (P/N: GPOE-XM81-8P-R10)</p>	
<p>M.2 & PCIe mini expansion card (P/N: GPOE-XM81-8P-R10)</p>	
<p>2-slot backplane (PCIe x16 & PCIe x4) (P/N: TXCBP-XM81-2A-R10)</p>	
<p>2-slot backplane (two PCIe x8) (P/N: TXCBP-XM81-2B-R10)ss</p>	

Optional	
<p>4-slot backplane (PCIe x16 & two PCIe x4 & PCIe x1) (P/N: TXCBP-XM81-4A-R10)</p>	
<p>4-slot backplane (two PCIe x8 & two PCIe x4) (P/N: TXCBP-XM81-4B-R10)</p>	
<p>4-slot backplane (PCIe x16 & PCIe x4 & two PCI) (P/N: TXCBP-XM81-4C-R10)</p>	
<p>4-slot backplane (PCIe x16 & two PCIe x4 & PCIe x1) (P/N: TXCBP-XM81-G1-PW-R10)</p>	
<p>4-slot backplane (two PCIe x8 & two PCIe x4) (P/N: TXCBP-XM81-G2-PW-R10)</p>	
<p>Expansion power board (P/N: IDD-X1228150-R10)</p>	

TANK-XM811

Optional	
3-slot chassis (P/N: TXC-XM81-3S-R10)	
4-slot chassis (P/N: TXC-XM81-4S-R10)	
4-slot chassis (full-length graphics card support) (P/N: TXC-XM81-G1-R10)	
6-slot chassis (two full-length graphics card support) (P/N: TXC-XM81-G2-R10)	
Expansion fan module (P/N: SF-TANK-XM81-R10)	

NOTE:

1. TXCBP-XM81 series backplane needs to be used with TXC-XM81 series chassis

Chapter

3

Installation

TANK-XM811

3.1 Installation Precautions



CAUTION:

The TANK-XM811 Series has more than one power supply connection point.

To reduce the risk of electric shock, disconnect all power sources before installing or servicing the TANK-XM811 Series.

During installation, be aware of the precautions below:

- **Read the user manual:** The user manual provides a complete description of the TANK-XM811 Series, installation instructions and configuration options.
- **DANGER! Disconnect Power:** Power to the TANK-XM811 Series must be disconnected during the installation process, or before any attempt is made to access the rear panel. Electric shock and personal injury might occur if the rear panel of the TANK-XM811 Series is opened while the power cord is still connected to an electrical outlet.
- **Qualified Personnel:** The TANK-XM811 Series must be installed and operated only by trained and qualified personnel. Maintenance, upgrades, or repairs may only be carried out by qualified personnel who are familiar with the associated dangers.
- **Air Circulation:** Make sure there is sufficient air circulation when installing the TANK-XM811 Series. The TANK-XM811 Series's cooling vents must not be obstructed by any objects. Leave at least 5 cm of clearance around the TANK-XM811 Series to prevent overheating.
- **Grounding:** The TANK-XM811 Series should be properly grounded. The voltage feeds must not be overloaded. Adjust the cabling and provide external overcharge protection per the electrical values indicated on the label attached to the back of the TANK-XM811 Series.

3.2 Back Cover Removal

Before installing or maintaining the internal components, the back cover must be removed

from the TANK-XM811. Follow the steps below to complete the task.

Step 1: Turn the TANK-XM811 over and remove the 6 screws on the back cover.

Step 2: Take off the back cover (Figure 3-1).

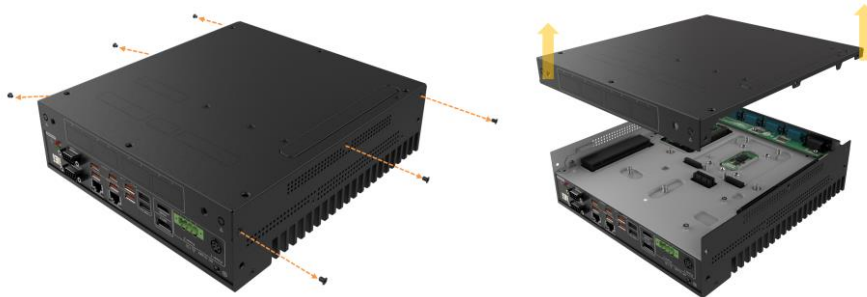


Figure 3-1: Remove the Cover

3.3 CPU Installation

To replace the CPU, you need to remove the motherboard first. Follow the steps below to complete the task.

Step 1: Remove the 11 spring screws on the motherboard, and then take out the motherboard (including the motherboard holder) (Figure 3-2).

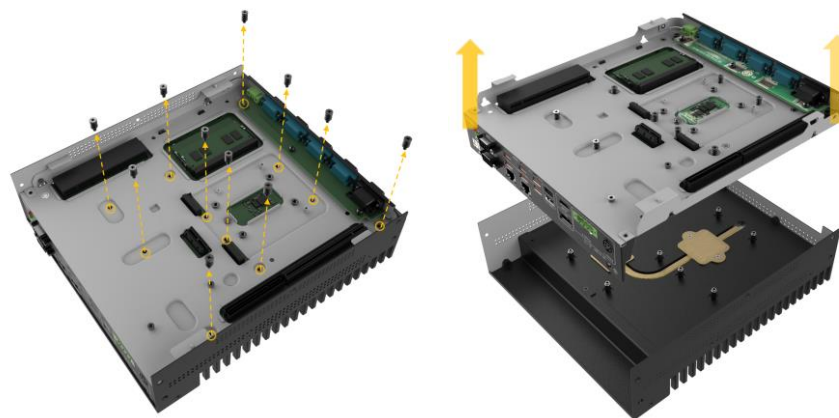


Figure 3-2: Motherboard Removal

Step 2: Pull the lever of the CPU buckle, remove the CPU protection cover, install the CPU at the notch, and fasten the lever down in the buckle (Figure 3-3).

TANK-XM811

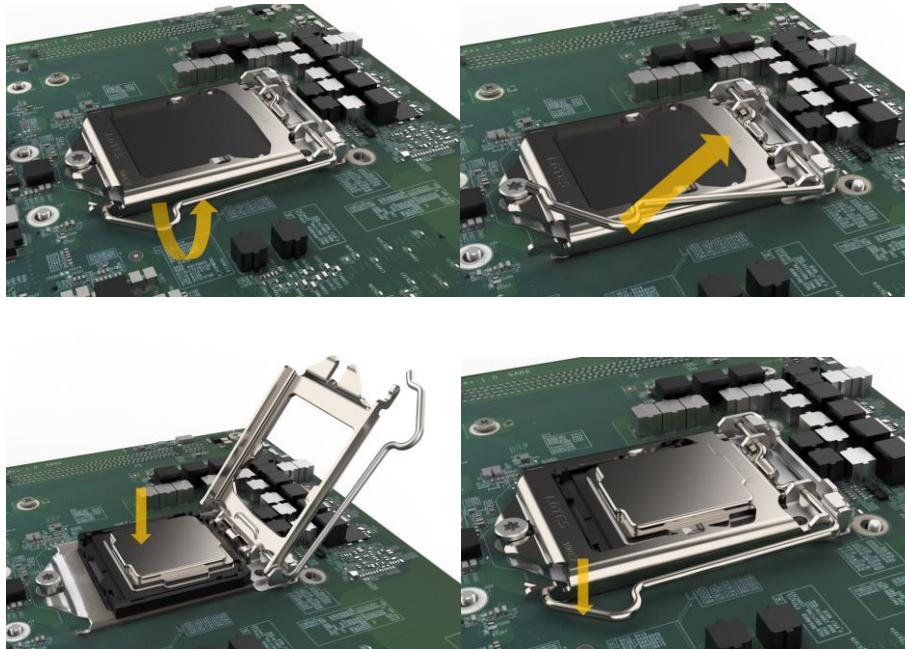


Figure 3-3: CPU Installation

Step 3: Place a thermal pad on the heat conductive block of CPU (Figure 3-4).

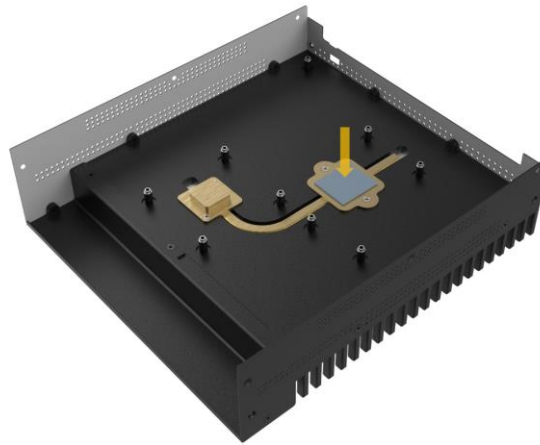


Figure 3-4: CPU Thermal Pad Installation

Step 4: Align the motherboard (together with the motherboard holder) with the 4 positioning rods on the 2 sides, place it on the heat sink, and lock the motherboard with 11 spring screws. (Figure 3-5)



Figure 3-5: Motherboard Installation

3.4 Memory Installation

The TANK-XM811 is pre-installed with an 8GB or 16GB memory module. Users can add or replace memory with different capacity by themselves, the installation procedures are described below.

- Step 1:** Open the two handles of the memory slot.
- Step 2:** Remove the old memory module and insert a new memory module.
Carefully align the memory module so the notch on the memory lines up with the notch on the memory socket.
- Step 3:** Once aligned, press down until the memory module is properly seated and the two handles fully clip into place (**Figure 3-6**)

TANK-XM811

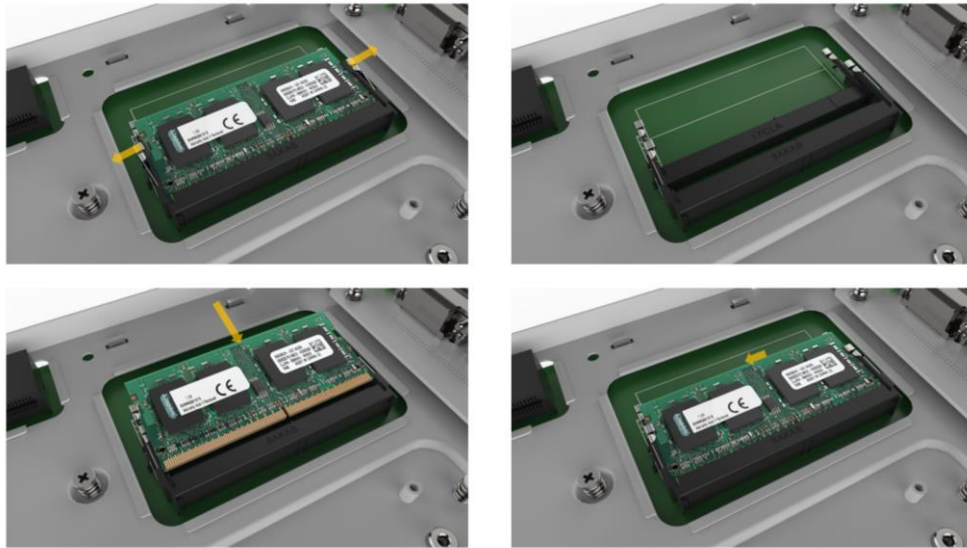


Figure 3-6: Memory Installation

3.5 Storage Installation

The TANK-XM811 supports two types of storage, one M.2 M Key & one 2.5" SSD

3.5.1 M.2 SSD Installation

Remove the M.2 2280 reserved screws, install the M.2 2280 NVME card, and secure the card with the retention screw removed previously (**Figure 3-7**)

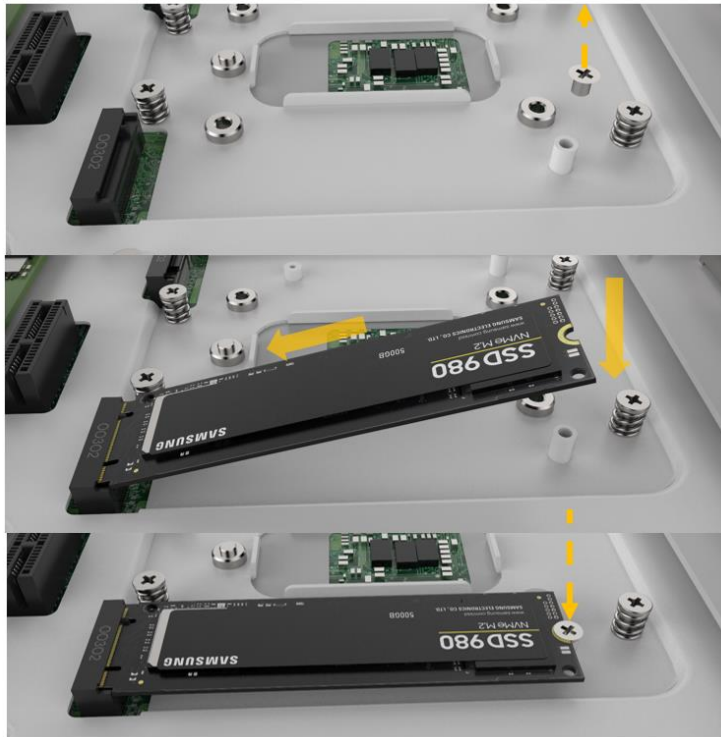


Figure 3-7: M.2 Installation

3.5.2 2.5-inch SSD Installation

Place the hard drive into the hard drive bracket and secure the HDD bracket with the hard drive using four screws (**Figure 3-8**)



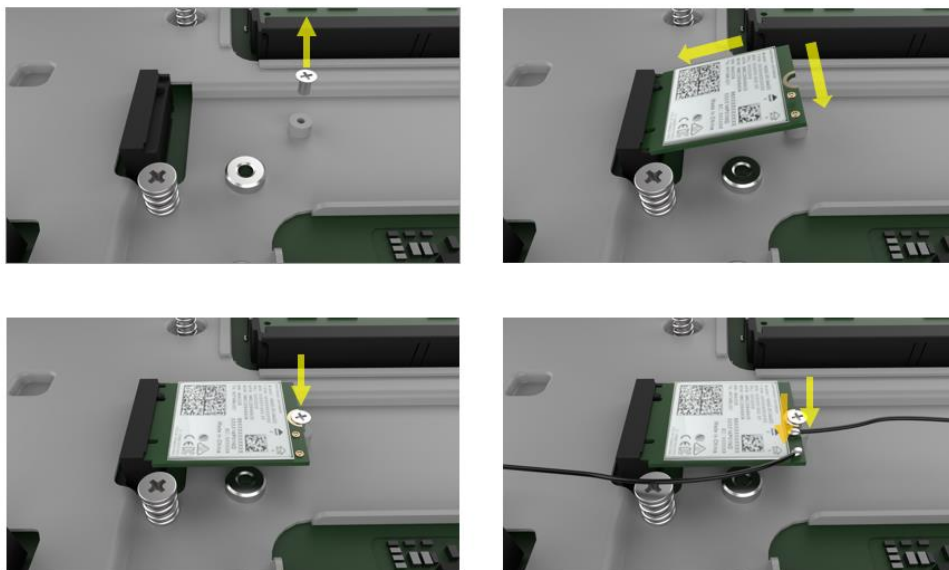
Figure 3-8: HDD Installation

3.6 Wi-Fi Module Installation (Optional)

The Wi-Fi module is an optional accessory. You can purchase it from IEI or other providers. Note that you have to purchase Wi-Fi module, internal antenna and external antenna. It is suggested to purchase an internal antenna longer than 200mm.

To install the Wi-Fi module, follow the steps below.

- Step 1:** Remove the M.2 A key retention screw.
- Step 2:** Insert the Wi-Fi module (IEI P/N: EMB-WIFI-KIT0213-R10, including one Intel AX210 wireless Bluetooth function module, two 300mm internal antennas and two 108mm external antennas) and secure the screw.
- Step 3:** Secure one end of the internal antenna to the Wi-Fi module.
- Step 4:** Knock out the reserved antenna holes on the chassis, and secure the other end of the internal antenna on the chassis.
- Step 5:** Install the external antennas(**Figure 3-9**)



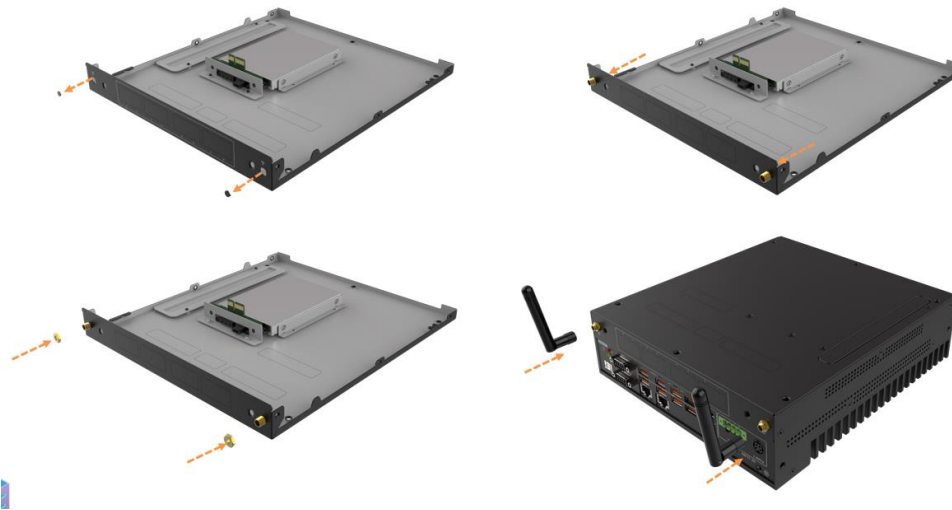


Figure 3-9: Wi-Fi Module and Wi-Fi Antenna Installation

3.7 Back Cover Installation

Install the back cover, and fasten the 6 screws on the side (**Figure 3-10**)



Figure 3-10: Back Cover Installation

3.8 Mounting the System with Mounting Brackets

To mount the embedded system onto a wall or some other surface using the two mounting brackets, please follow the steps below.

- Step 1:** Turn the embedded system over.
- Step 2:** Align the retention screw holes in each bracket with the corresponding retention screw holes on the bottom surface

TANK-XM811

- Step 3:** Secure the brackets to the system by inserting retention screws into each bracket (**Figure 3-11**).



Figure 3-11: Mounting Bracket Retention Screws

- Step 4:** Drill holes in the intended installation surface.
- Step 5:** Align the mounting holes in the sides of the mounting brackets with the predrilled holes in the mounting surface.
- Step 6:** Insert four retention screws, three in each bracket, to secure the system to the wall.

3.9 External Peripheral Interface Connectors

The TANK-XM811 Series has the following connectors. Detailed descriptions of the connectors can be found in the subsections below.

- AT/ATX power mode switch

- Digital I/O
- Ethernet
- Power button
- Power DC jack
- Power terminal block
- HDMI
- DP++
- RS-232/422/485
- USB

3.9.1 AT/ATX Power Mode Selection

The TANK-XM811 Series supports AT and ATX power modes. The setting can be made through the AT/ATX power mode switch on the external peripheral interface panel as shown below (**Figure 3-12**)..

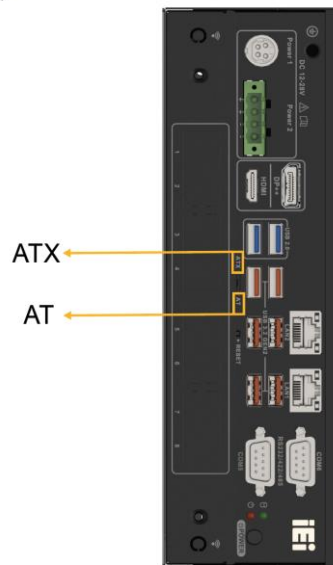


Figure 3-12: AT/ATX Power Mode Switch

3.9.2 System Fan Connector

The system fan connector can be connected to an external expansion fan (**Figure 3-13**).

TANK-XM811

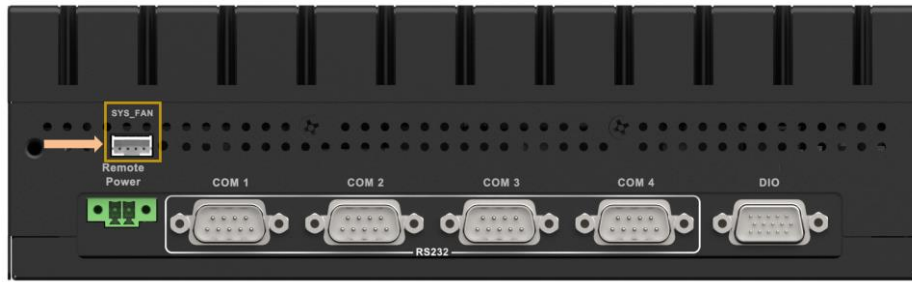


Figure 3-13: SYS_FAN Connector

3.9.3 Digital Input / Output Connector

The digital I/O connector provides programmable input and output for external devices. The pinouts for the digital I/O connector are listed in the table below (Table 3-1) (Figure 3-14).

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	GND	2	DIN0
3	DIN1	4	DIN2
5	DIN3	6	DIN4
7	DIN5	8	GND
9	DOUT0	10	DOUT1
11	DOUT2	12	DOUT3
13	DOUT4	14	DOUT5
15	+5VS		

Table 3-1: Digital I/O Connector Pinouts

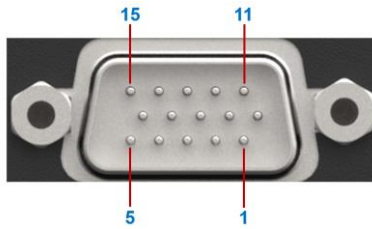


Figure 3-14: DIO Connector

3.9.4 HDMI/DP Connector

To connect the HDMI/DP devices, please plug in HDMI/DP connector in the right direction as shown below:



Figure 3-15: HDMI/DP Connection

3.9.5 LAN Connectors

The LAN connectors allow connection to an external network.

Step 1: **Locate the RJ-45 connectors.** The locations of the RJ-45 connectors are shown in **Figure 3-17**.

TANK-XM811

Step 2: Align the connectors. Align the RJ-45 connector on the LAN cable with one of the RJ-45 connectors on the TANK-XM811 Series. See **Figure 3-16**.

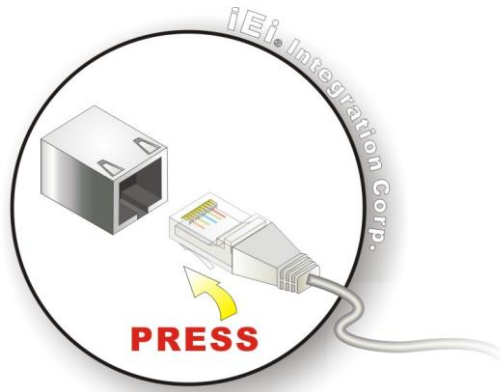


Figure 3-16: LAN Connection

Step 3: Insert the LAN cable RJ-45 connector. Once aligned, gently insert the LAN cable RJ-45 connector into the on-board RJ-45 connector.



Figure 3-17: RJ-45 Ethernet Connector

The RJ-45 Ethernet connector has two status LEDs, one green and one yellow. The green LED indicates activity on the port and the yellow LED indicates the port is linked. See Table 3-2

Activity/Link LED		Speed LED	
STATUS	DESCRIPTION	STATUS	DESCRIPTION
Off	No link	Off	100 Mbps connection
SSYellow	Linked	Orange	1 Gbp connection
Blinking	TX/RX activity	Green	2.5 Gbps connection

Table 3-2: RJ-45 Ethernet Connector LEDs

3.9.6 Power Input, 4-pin Terminal Block

The power connector connects the leads of a 12 V~28 V DC power supply into the terminal block. Make sure that the power and ground wires are attached to the correct sockets of the connector (**Figure 3-18**).

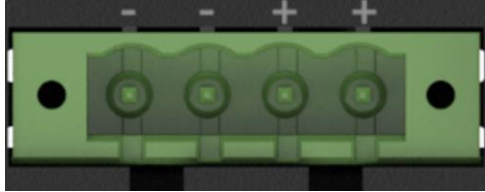


Figure 3-18: 4-pin Terminal Block

3.9.7 Power Input, 4-pin DIN Connector

The power connector connects to the 12 V~28 V DC power adapter (**Figure 3-19**).

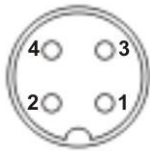


Figure 3-19: Power Input Connector

3.9.8 DB-9 RS-232/422/485 Serial Port Connectors

The system has two RS-232/422/485 & four RS232 serial port connectors. The pinouts for the serial ports are listed in the table below (Table 3-3) (Figure 3-20).

PIN NO.	RS232	RS422	RS485
1	DCD#	TX-	TX-
2	RXD	TX+	TX+
3	TXD	RX+	
4	DTR#	RX-	
5	GND		
6	DSR#		
7	RTS#		
8	CTS#		
9	RI#		

Table 3-3: RS-232 (COM1~COM4) & RS-232/422/485 (COM5~COM6) Connector Pinouts

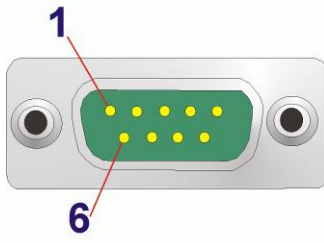


Figure 3-20: DB-9 RS-232/422/485 Serial Port Connector

3.9.9 Remote Power Connector

This remote power switch connector can be connected to an external switch for remote control of power on and off (Figure 3-21)



Figure 3-21: Remote Power Connector

3.10 Powering On/Off the System



WARNING:

Make sure a power supply with the correct input voltage is being fed into the system. Incorrect voltages applied to the system may cause damage to the internal electronic components and may also cause injury to the user.

- **Power on** the system: press the power button for 3 seconds
- **Power off** the system: press the power button for 6 seconds
- The power of this system can be less than 250w-20A.

TANK-XM811

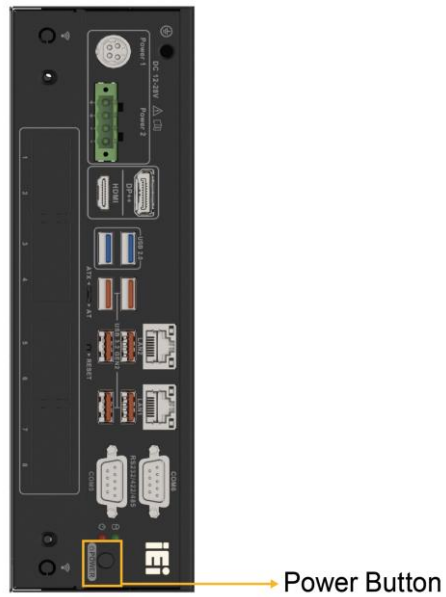


Figure 3-22: Power Button

3.11 Power

There are two power connectors on the rear panel. Power 1 connector is a DIN connector block that supports ACC On signal. Power 2 connector is a 4-pin terminal that can directly connect to a power adapter. The supported power input voltages are:

- **Power 1 (DIN connector):** 12 V ~ 28 V
- **Power 2 (terminal block):** 12 V ~ 28 V

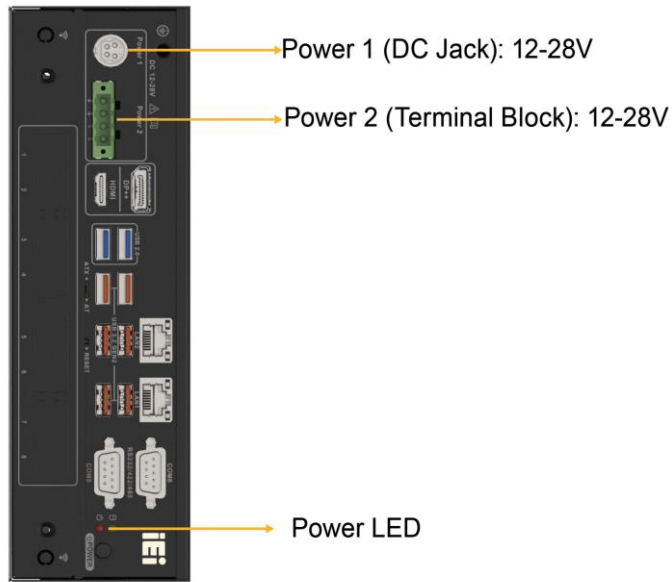


Figure 3-23: Power Connectors

Power LED Indicator	Description
Breathing Orange	Standby mode.
Solid blue	Power-on mode.

Table 3-4: Power LED Indicators Description



NOTE:

The power LED turns off when the power cable is unplugged from the system.

TANK-XM811

3.12 Available Drivers

All the drivers for the TANK-XM811 Series are available on IEI Resource Download Center (<https://download.ieiworld.com>). Type TANK-XM811 Series and press Enter to find all the relevant software, utilities, and documentation.

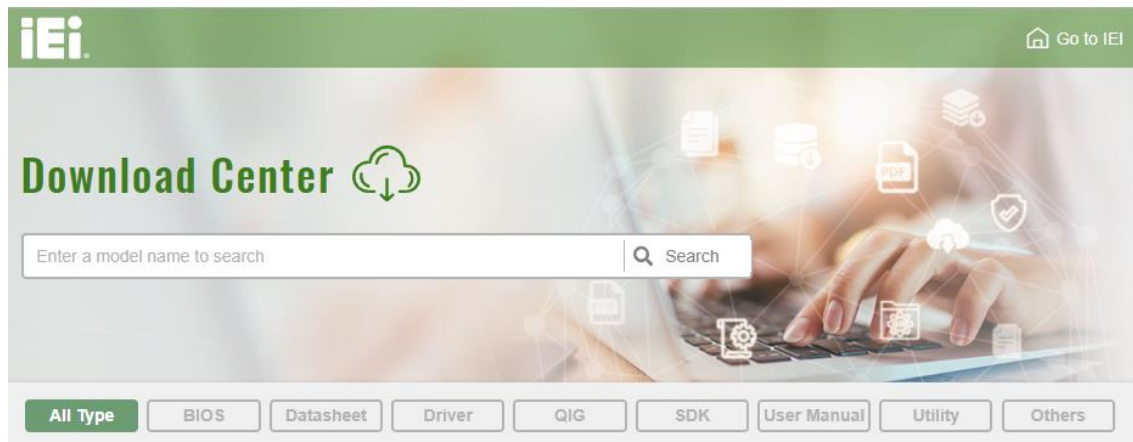
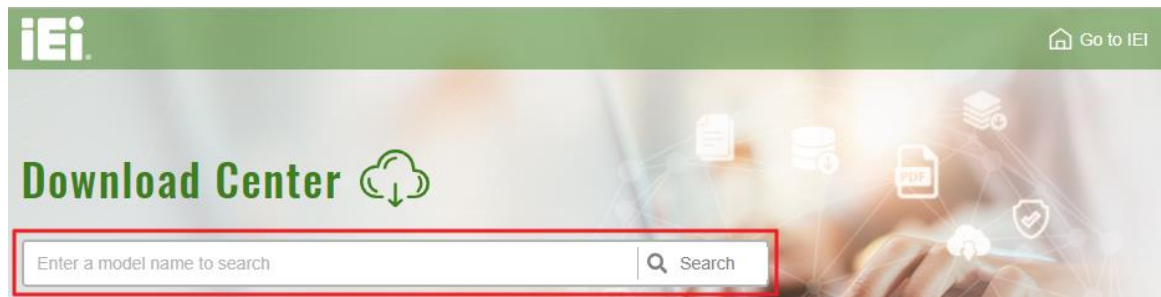


Figure 3-24: IEI Resource Download Center

3.12.1 Driver Download

To download drivers from IEI Resource Download Center, follow the steps below.

Step 1: Go to <https://download.ieiworld.com>. Type TANK-XM811 Series and press Enter.



Step 2: All product-related software, utilities, and documentation will be listed. You can choose **Driver** to filter the result.

[All Type](#)
[BIOS](#)
[Datasheet](#)
[Driver](#)
[QIG](#)
[SDK](#)
[User Manual](#)
[Utility](#)
[Others](#)

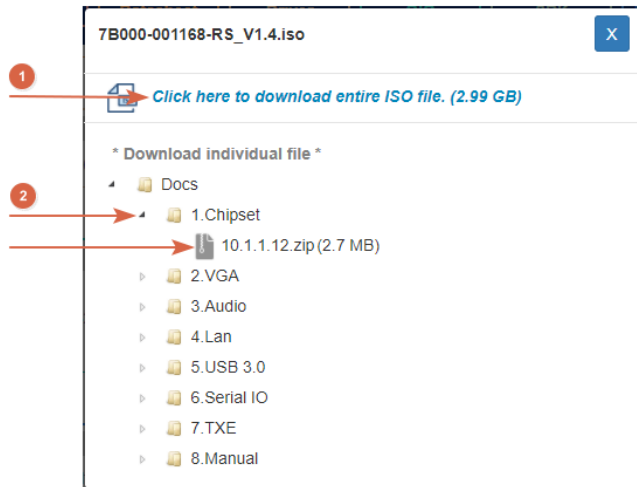
WAFER-BT-i1 Product Info ▶

[Embedded Computer](#) ▶ [Single Board Computer](#) ▶ [Embedded Board](#)
 3.5" SBC with Intel® 22nm Atom™/Celeron® on-board SoC

Driver

File Name	Published	Version	File Checksum
7B000-001033-RS V2.3.iso (2.23 GB)	2017/10/03	2.30	3B2DB1F792779A93A8F50DDBC3943E30

Step 3: Click the driver file name on the page and you will be prompted with the following window. You can download the entire ISO file (❶), or click the small arrow to find an individual driver and click the file name to download (❷).



NOTE:

To install software from the downloaded ISO image file in Windows 10 (or later), double-click the ISO file to mount it as a virtual drive to view its content.

TANK-XM811

3.13 Maintenance

To configure the jumper settings, please follow the steps below.

- Step 1:** Remove the top cover. See Figure 3-2.
- Step 2:** Locate the jumper on the embedded motherboard.
- Step 3:** Make the jumper settings in accordance with the settings described and defined in the following sections.

3.13.1 Flash Descriptor Security Override Jumper

The Descriptor Security Override jumper (J_FLASH1) allows users to enable or disable the ME firmware update. Refer to Figure 3-25 and Table 3-5 for the jumper location and settings.

Setting	Description
Short 1-2	Disabled (default)
Short 2-3	Enabled

Table 3-5: Flash Descriptor Security Override Jumper Settings

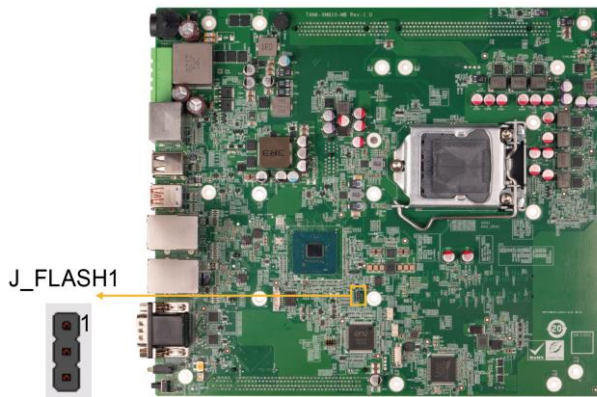


Figure 3-25 Flash Descriptor Security Override Jumper Location

To update the ME firmware, please follow the steps below.

TANK-XM811

- Step 1:** Before turning on the system power, short the Flash Descriptor Security Override jumper.
- Step 2:** Update the BIOS and ME firmware, and then turn off the system power.
- Step 3:** Remove the metal clip on the Flash Descriptor Security Override jumper or return to its default setting (open).
- Step 4:** Restart the system. The system will reboot to complete the ME firmware update.

Chapter

4

System Motherboard

4.1 Overview

This chapter details all the jumpers and connectors of the system motherboard.

4.1.1 Layout

The figures below show all the connectors and jumpers of the system motherboard.

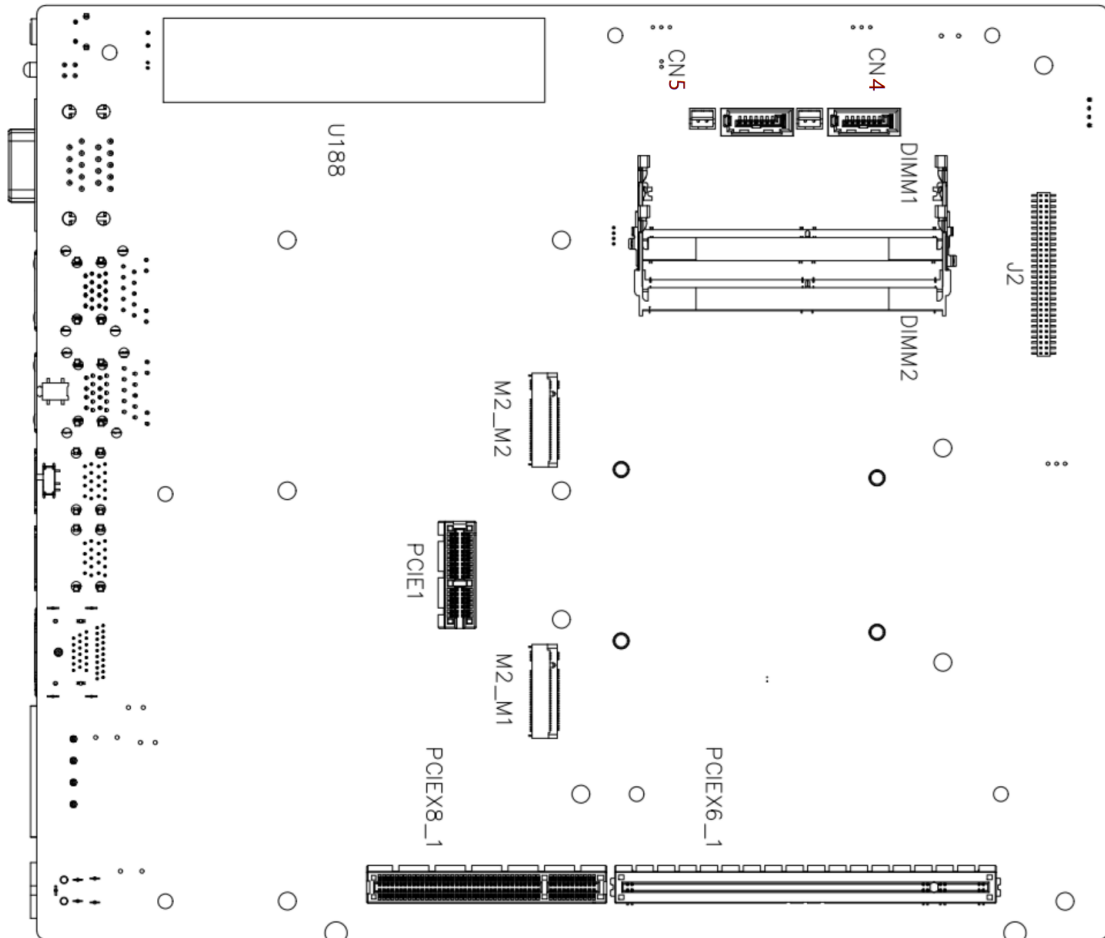


Figure 4-1: System Motherboard (Front)

TANK-XM811

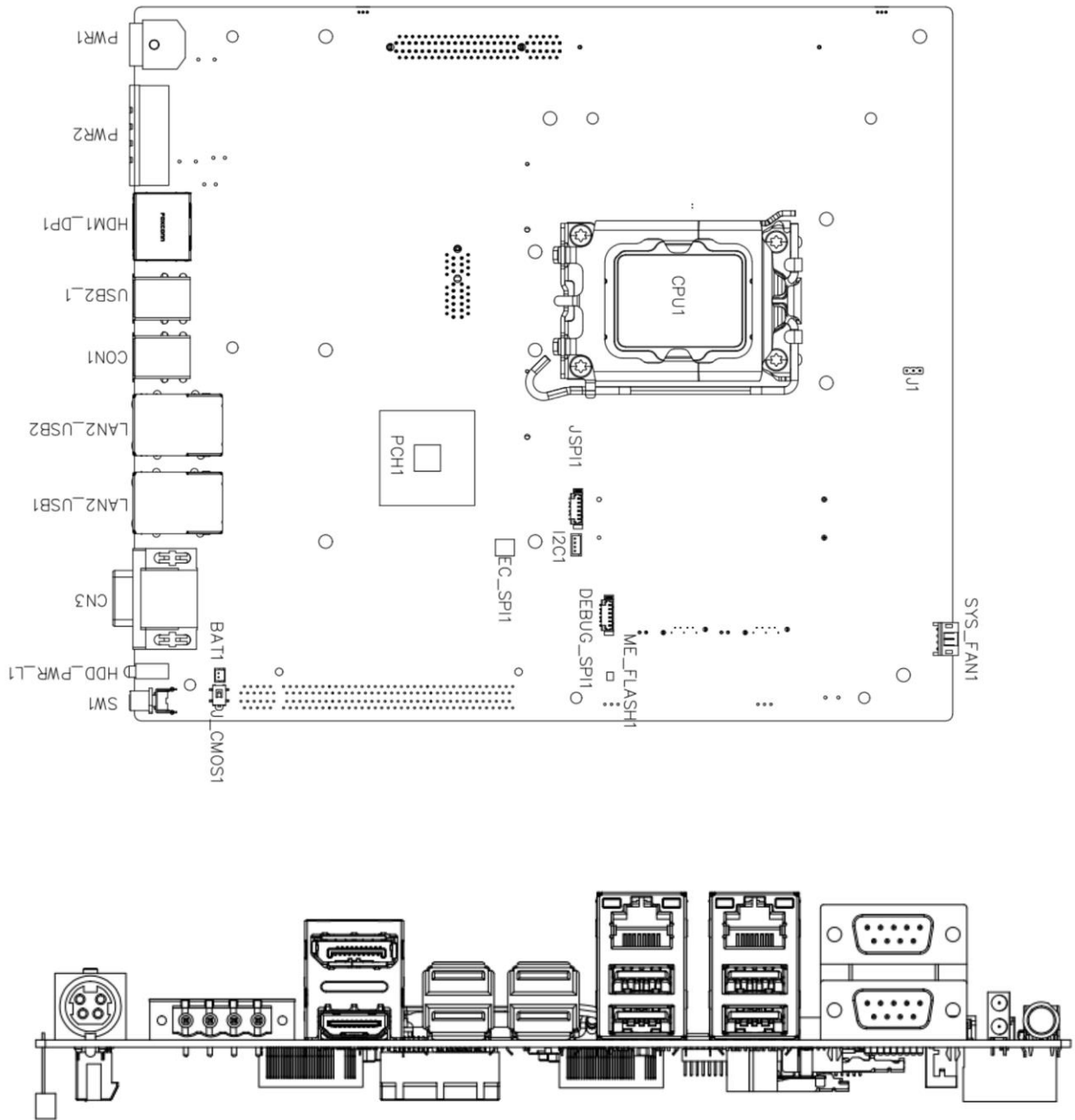


Figure 4-2: System Motherboard (Rear)

4.2 Internal Peripheral Connectors

The table below shows a list of the internal peripheral interface connectors on the system motherboard. Pinouts of these connectors can be found in the following sections.

Connector	Type	Label
Clear CMOS switch	4-pin Switch	J_CMOS1
Battery connector	2-pin header	BAT1
BIOS programming connector	6-pin box header	JSPI1
EC programming connector	8-pin header	EC_JSP1
EC debug card connector	6-pin box header	DBG _JSP1
Flash override jumper	3-pin header	ME_FLASH1
I ² C BUS connector	4-pin box header	I2C1
M.2 slot (PCIe x2 interface)	M.2 M-key slot	M2_M1
M.2 slot (PCIe x1/USB2.0 interface)	M.2 A-key slot	M2_M2
HDD backplane connector	PCIe x1 slot	PCIEX1_1
DDR4 memory slot	DDR4 memory slot	DIMM1, DIMM2
PCIe backplane connector	backplane connector	PCIEX16_1, PCIEX8_1
PCIe IO board connector	PCIe x16 slot	U188
Thermal sensor connector	3-pin Connector	CN4,CN5

Table 4-1: Peripheral Interface Connectors

4.2.1 Clear CMOS Switch (J_CMOS1)

PIN NO.	DESCRIPTION
Open	Normal Operation (Default)
Push	Clear CMOS Setup

Table 4-2: Clear CMOS Switch (J_CMOS1)

4.2.2 BIOS Programming Connector (JSPI1)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	+V3.3M_SPI_CON	2	SPI_CS#0_SW
3	SPI_SO_SW	4	SPI_CLK_SW
5	SPI_SI_SW	6	GND

Table 4-3: BIOS Programming Connector Pinouts (JSPI1)

4.2.3 EC Programming Connector (EC_SPI1)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	EC_SPI_CS#_R	2	+V3.3A_EC
3	EC_SPI_MISO_R	4	NC
5	EC_DET_FLASH	6	EC_SPI_CLK_R
7	GND	8	EC_SPI_MOSI_R

Table 4-4: EC Programming Connector (EC_SPI1)

4.2.4 EC Debug Card Connector (DEBUG_SPI1)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	NC	2	EDICS
3	EDIDO	4	EDICLK
5	EDIDI	6	GND

Table 4-5: EC Debug Card Connector (DEBUG_SPI1)

4.2.5 System Fan Connector (SYS_FAN1)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	GND	2	VCC12V
3	FANIO	4	PWM

Table 4-6: System Fan Connector (SYS_FAN1)

4.2.6 Battery Connector (BAT1)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	VBATT	2	GND

Table 4-7: Battery Connector (BAT1)

4.3 External Interface Panel Connectors

The table below shows a list of the external interface panel connectors on the system motherboard. Pinouts of these connectors can be found in the following sections.

Connector	Type	Label
Power input connector	4-pin DC jack	Power 1
Power input connector	4-pin terminal block	Power 2
DP and HDMI connector	DisplayPorts, HDMI	DP++ HDMI
USB 3.2 Gen 2	USB 3.2 Gen 2	USB_CN1,USB_CN2
Ethernet and USB 3.2 Gen 2 combo connectors	RJ-45, USB 3.2 Gen 2 Type A	LAN1_USB1, LAN1_USB2,

Connector	Type	Label
RS-232/422/485 connector	DB-9	COM5, COM6
RESET switch	4-pin switch	RESET
AT/ATX mode switch	2-pin switch	AT/ATX
HDD+System LED	HDD+system LED	HDD_PWR
Power button connector	4-pin switch	POWER
RS-232 connector	DB-9	COM1, COM2, COM3, COM4
System fan connector	4-pin box header	SYS_FAN
Digital I/O connector	DB-15	DIO
Remote power connector	2-pin terminal block	Remote Power

Table 4-8: Rear Panel Connectors

4.3.1 LAN Connectors

Pin	Description	Pin	Description
1	MDIA3-	5	MDIA1+
2	MDIA3+	6	MDIA2+
3	MDIA2-	7	MDIA0-
4	MDIA1-	8	MDIA0+

Table 4-9: Ethernet Connector Pinouts

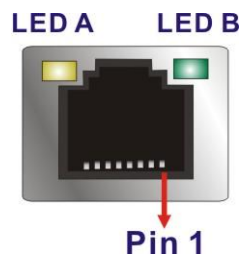


Figure 4-3: Ethernet Connector

LED	Description	LED	Description
A	on: linked blinking: data is being sent/received	B	off: 100 Mb/s orange: 1000 Mb/s green: 2.5 Gb/s

Table 4-10: Connector LEDs

4.3.2 Power Input Connector, DC Jack (PWR1)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	DC_IN1	2	GND
3	DC_IN1	4	GND
5	GND		

Table 4-11: Power Input Connector (PWR1)

4.3.3 Power Input Connector, Terminal Block (PWR2)

PIN NO.	DESCRIPTION	PIN NO.	DESCRIPTION
1	DC_IN2	2	DC_IN2
3	GND	4	GND

Table 4-12: Power Input Connector (PWR2)

Appendix

A

Regulatory Compliance

DECLARATION OF CONFORMITY



This equipment is in conformity with the following EU directives:

- EMC Directive (2004/108/EC, 2014/30/EU)
- Low-Voltage Directive (2006/95/EC, 2014/35/EU)
- RoHS II Directive (2011/65/EU, 2015/863/EU)

If the user modifies and/or install other devices in the equipment, the CE conformity declaration may no longer apply.

If this equipment has telecommunications functionality, it also complies with the requirements of the Radio Equipment Directive 2014/53/EU.

English

IEI Integration Corp declares that this equipment is in compliance with the essential requirements and other relevant provisions of Directive 2014/53/EU.

Български [Bulgarian]

IEI Integration Corp. декларира, че този оборудване е в съответствие със съществените изисквания и другите приложими правила на Директива 2014/53/EU.

Česky [Czech]

IEI Integration Corp tímto prohlašuje, že tento zařizení je ve shodě se základními požadavky a dalšími příslušnými ustanoveními směrnice 2014/53/EU.

Dansk [Danish]

IEI Integration Corp erklærer herved, at følgende udstyr overholder de væsentlige krav og øvrige relevante krav i direktiv 2014/53/EU.

Deutsch [German]

IEI Integration Corp, erklärt dieses Gerät entspricht den grundlegenden Anforderungen und den weiteren entsprechenden Vorgaben der Richtlinie 2014/53/EU.

TANK-XM811

Eesti [Estonian]

IEI Integration Corp deklareerib seadme seadme vastavust direktiivi 2014/53/EÜ põhinõuetele ja nimetatud direktiivist tulenevatele teistele asjakohastele sätetele.

Español [Spanish]

IEI Integration Corp declara que el equipo cumple con los requisitos esenciales y cualesquiera otras disposiciones aplicables o exigibles de la Directiva 2014/53/EU.

Ελληνική [Greek]

IEI Integration Corp ΔΗΛΩΝΕΙ ΟΤΙ ΕΞΟΠΛΙΣΜΟΣ ΣΥΜΜΟΡΦΩΝΕΤΑΙ ΠΡΟΣ ΤΙΣ ΟΥΣΙΩΔΕΙΣ ΑΠΑΙΤΗΣΕΙΣ ΚΑΙ ΤΙΣ ΛΟΙΠΕΣ ΣΧΕΤΙΚΕΣ ΔΙΑΤΑΞΕΙΣ ΤΗΣ ΟΔΗΓΙΑΣ 2014/53/EU.

Français [French]

IEI Integration Corp déclare que l'appareil est conforme aux exigences essentielles et aux autres dispositions pertinentes de la directive 2014/53/EU.

Italiano [Italian]

IEI Integration Corp dichiara che questo apparecchio è conforme ai requisiti essenziali ed alle altre disposizioni pertinenti stabilite dalla direttiva 2014/53/EU.

Latviski [Latvian]

IEI Integration Corp deklarē, ka iekārta atbilst būtiskajām prasībām un citiem ar to saistītajiem noteikumiem Direktīvas 2014/53/EU.

Lietuvių [Lithuanian]

IEI Integration Corp deklaruoja, kad šis įranga atitinka esminius reikalavimus ir kitas 2014/53/EU Direktyvos nuostatas.

Nederlands [Dutch]

IEI Integration Corp dat het toestel toestel in overeenstemming is met de essentiële eisen en de andere relevante bepalingen van richtlijn 2014/53/EU.

Malti [Maltese]

IEI Integration Corp jiddikjara li dan prodott jikkonforma mal-ħtiġijiet essenzjali u ma provvedimenti oħrajn relevanti li hemm fid-Dirrettiva 2014/53/EU.

Magyar [Hungarian]

IEI Integration Corp nyilatkozom, hogy a berendezés megfelel a vonatkozó alapvető követelményeknek és az 2014/53/EU irányelv egyéb előírásainak.

Polski [Polish]

IEI Integration Corp oświadcza, że wyrobu jest zgodny z zasadniczymi wymogami oraz pozostałymi stosownymi postanowieniami Dyrektywy 2014/53/EU.

Português [Portuguese]

IEI Integration Corp declara que este equipamento está conforme com os requisitos essenciais e outras disposições da Directiva 2014/53/EU.

Româna [Romanian]

IEI Integration Corp declară că acest echipament este în conformitate cu cerințele esențiale și cu celelalte prevederi relevante ale Directivei 2014/53/EU.

Slovensko [Slovenian]

IEI Integration Corp izjavlja, da je ta opreme v skladu z bistvenimi zahtevami in ostalimi relevantnimi določili direktive 2014/53/EU.

Slovensky [Slovak]

IEI Integration Corp týmto vyhlasuje, že zariadenia spĺňa základné požiadavky a všetky príslušné ustanovenia Smernice 2014/53/EU.

Suomi [Finnish]

IEI Integration Corp vakuuttaa täten että laitteen on direktiivin 2014/53/EU oleellisten vaatimusten ja sitä koskevien direktiivin muiden ehtojen mukainen.

Svenska [Swedish]

IEI Integration Corp förklarar att denna utrustningstyp står i överensstämmelse med de väsentliga egenskapskrav och övriga relevanta bestämmelser som framgår av direktiv 2014/53/EU.



FCC WARNING

This equipment complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- This device may not cause harmful interference, and
- This device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

Federal Communication Commission Interference Statement

This equipment has been assembled with components that comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Appendix

B

Safety Precautions

TANK-XM811

B.1 Safety Precautions



WARNING:

The precautions outlined in this appendix should be strictly followed. Failure to follow these precautions may result in permanent damage to the TANK-XM811 Series.

Please follow the safety precautions outlined in the sections that follow:

B.1.1 General Safety Precautions

Please ensure the following safety precautions are adhered to at all times.

- ***Make sure the power is turned off and the power cord is disconnected*** when moving, installing or modifying the system.
- ***Do not apply voltage levels that exceed the specified voltage range.*** Doing so may cause fire and/or an electrical shock.
- ***Electric shocks can occur*** if opened while still powered on.
- ***Do not drop or insert any objects*** into the ventilation openings.
- ***If considerable amounts of dust, water, or fluids enter the system***, turn off the power supply immediately, unplug the power cord, and contact the system vendor.
- **DO NOT:**
 - Drop the system against a hard surface.
 - In a site where the ambient temperature exceeds the rated temperature

B.1.2 Anti-static Precautions

**WARNING:**

Failure to take ESD precautions during the installation of the TANK-XM811 Series may result in permanent damage to the TANK-XM811 Series and severe injury to the user.

Electrostatic discharge (ESD) can cause serious damage to electronic components, including the TANK-XM811 Series. Dry climates are especially susceptible to ESD. It is therefore critical that whenever the TANK-XM811 Series is opened and any of the electrical components are handled, the following anti-static precautions are strictly adhered to.

- ***Wear an anti-static wristband:*** Wearing a simple anti-static wristband can help to prevent ESD from damaging any electrical component.
- ***Self-grounding:*** Before handling any electrical component, touch any grounded conducting material. During the time the electrical component is handled, frequently touch any conducting materials that are connected to the ground.
- ***Use an anti-static pad:*** When configuring or working with an electrical component, place it on an anti-static pad. This reduces the possibility of ESD damage.
- ***Only handle the edges of the electrical component:*** When handling the electrical component, hold the electrical component by its edges.

TANK-XM811

B.1.3 Product Disposal

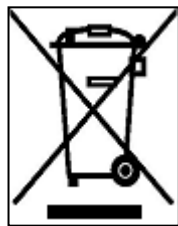


CAUTION:

Risk of explosion if battery is replaced by and incorrect type. Only certified engineers should replace the on-board battery.

Dispose of used batteries according to instructions and local regulations.

- Outside the European Union - If you wish to dispose of used electrical and electronic products outside the European Union, please contact your local authority so as to comply with the correct disposal method.
- Within the European Union - The device that produces less waste and is easier to recycle is classified as electronic device in terms of the European Directive 2012/19/EU (WEEE), and must not be disposed of as domestic garbage.



EU-wide legislation, as implemented in each Member State, requires that waste electrical and electronic products carrying the mark (left) must be disposed of separately from normal household waste. This includes monitors and electrical accessories, such as signal cables or power cords.

When you need to dispose of your display products, please follow the guidance of your local authority, or ask the shop where you purchased the product. The mark on electrical and electronic products only applies to the current European Union Member States.

Please follow the national guidelines for electrical and electronic product disposal.

B.2 Maintenance and Cleaning Precautions

When maintaining or cleaning the TANK-XM811 Series, please follow the guidelines below.

B.2.1 Maintenance and Cleaning

Prior to cleaning any part or component of the TANK-XM811 Series, please read the details below.

- The interior of the TANK-XM811 Series does not require cleaning. Keep fluids away from the TANK-XM811 Series interior.
- Be cautious of all small removable components when vacuuming the TANK-XM811 Series.
- Turn the TANK-XM811 Series off before cleaning the TANK-XM811 Series.
- Never drop any objects or liquids through the openings of the TANK-XM811 Series.
- Be cautious of any possible allergic reactions to solvents or chemicals used when cleaning the TANK-XM811 Series.
- Avoid eating, drinking and smoking within vicinity of the TANK-XM811 Series.

B.2.2 Cleaning Tools

Some components in the TANK-XM811 Series may only be cleaned using a product specifically designed for the purpose. In such case, the product will be explicitly mentioned in the cleaning tips. Below is a list of items to use when cleaning the TANK-XM811 Series.

- **Cloth** – Although paper towels or tissues can be used, a soft, clean piece of cloth is recommended when cleaning the TANK-XM811 Series.
- **Water or rubbing alcohol** – A cloth moistened with water or rubbing alcohol can be used to clean the TANK-XM811 Series.
- **Using solvents** – The use of solvents is not recommended when cleaning the TANK-XM811 Series as they may damage the plastic parts.
- **Vacuum cleaner** – Using a vacuum specifically designed for computers is one of the best methods of cleaning the TANK-XM811 Series. Dust and dirt can restrict the airflow in the TANK-XM811 Series and cause its circuitry to corrode.
- **Cotton swabs** - Cotton swabs moistened with rubbing alcohol or water are excellent tools for wiping hard to reach areas.
- **Foam swabs** - Whenever possible, it is best to use lint free swabs such as foam swabs for cleaning.

Appendix

C

Error Beep Code

C.1 PEI Beep Codes

Number of Beeps	Description
1	Memory not Installed
1	Memory was installed twice (InstallPeiMemory routine in PEI Core called twice)
2	Recovery started
3	DXE IPL was not found
3	DXE Core Firmware Volume was not found
4	Recovery failed
4	S3 Resume failed
7	Reset PPI is not available

C.2 DXE Beep Codes

Number of Beeps	Description
1	Invalid password
4	Some of the Architectural Protocols are not available
5	No Console Output Devices are found
5	No Console Input Devices are found
6	Flash update is failed
7	Reset protocol is not available
8	Platform PCI resource requirements cannot be met



NOTE:

If you have any question, please contact IEI for further assistance.

Appendix

D

Hazardous Materials Disclosure

D.1 RoHS II Directive (2015/863/EU)

The details provided in this appendix are to ensure that the product is compliant with the RoHS II Directive (2015/863/EU). The table below acknowledges the presences of small quantities of certain substances in the product, and is applicable to RoHS II Directive (2015/863/EU).

Please refer to the following table.

Part Name	Toxic or Hazardous Substances and Elements									
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (CR(VI))	Polybrominated Biphenyls (PBB)	Polybrominated Diphenyl Ethers (PBDE)	Bis(2-ethylhexyl) phthalate (DEHP)	Butyl benzyl phthalate (BBP)	Dibutyl phthalate (DBP)	Diisobutyl phthalate (DIBP)
Housing	O	O	O	O	O	O	O	O	O	O
Printed Circuit Board	O	O	O	O	O	O	O	O	O	O
Metal Fasteners	O	O	O	O	O	O	O	O	O	O
Cable Assembly	O	O	O	O	O	O	O	O	O	O
Fan Assembly	O	O	O	O	O	O	O	O	O	O
Power Supply Assemblies	O	O	O	O	O	O	O	O	O	O
Battery	O	O	O	O	O	O	O	O	O	O
<p>O: This toxic or hazardous substance is contained in all of the homogeneous materials for the part is below the limit requirement in Directive (EU) 2015/863.</p> <p>X: This toxic or hazardous substance is contained in at least one of the homogeneous materials for this part is above the limit requirement in Directive (EU) 2015/863.</p>										

TANK-XM811

D.2 China RoHS

此附件旨在确保本产品符合中国 RoHS 标准。以下表格标示此产品中某有毒物质的含量符合中国 RoHS 标准规定的限量要求。

本产品上会附有“环境友好使用期限”的标签,此期限是估算这些物质“不会有泄漏或突变”的年限。本产品可能包含有较短的环境友好使用期限的可替换元件,像是电池或灯管,这些元件将会单独标示出来。

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (CR(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
壳体	○	○	○	○	○	○
印刷电路板	○	○	○	○	○	○
金属螺帽	○	○	○	○	○	○
电缆组装	○	○	○	○	○	○
风扇组装	○	○	○	○	○	○
电力供应组装	○	○	○	○	○	○
电池	○	○	○	○	○	○

○: 表示该有毒有害物质在该部件所有物质材料中的含量均在 SJ/T11364-2014 與 GB/T26572-2011 标准规定的限量要求以下。

X: 表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T11364-2014 與 GB/T26572-2011 标准规定的限量要求。